



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,603

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND
PACKAGING OF FLIP CHIP
CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6862

Examiner: Unknown

Group Art Unit: 2823

Attorney Docket No.: 2269-4974.2US
(00-0693.02/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 4, 2005
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of U.S. patents and U.S. patent publications are not being submitted pursuant to M.P.E.P. 609 III A(2). The listed documents were cited by the Office in co-pending application Serial No. 10/150,901, filed on May 17, 2002, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

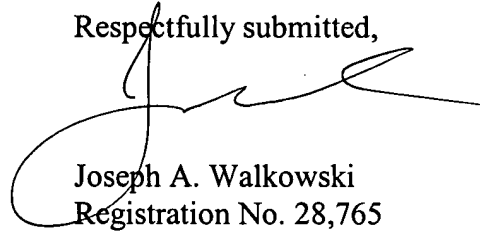
<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US – 5,468,995	11/21/1995	Higgins, III
US – 6,610,559	8/26/2003	Wang et al.
US – 6,239,496	5/29/2001	Asada

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

Serial No. 10/829,603

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Therefore, no fee is required.

Respectfully submitted,



Joseph A. Walkowski
Registration No. 28,765
Attorney for Applicant
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: November 4, 2005
JAW/dn:slm
Enclosures: Form PTO/SB/08
Document in ProLaw

PTO/SB/08A (10-01)
Approved for use through 10/31/2002. OMB 0651-0031
U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				<i>Complete if Known</i>	
				Application Number	10/829,603
				Filing Date	April 22, 2004
				First Named Inventor	Teck Kheng Lee
				Group Art Unit	2823
				Examiner Name	Unknown
				Attorney Docket Number	2269-4974.2US (00-0693.02/US)
Sheet	1	of	1		